

# DZ2406200L

## Silicon epitaxial planar type

For constant voltage / For surge absorption circuit  
Capability of withstanding a high surge type  
DZ2W062 in Power type package

### ■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

### ■ Marking Symbol: FJ

### ■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	500	mA
Forward current	IF	400	mA
Total power dissipation <sup>*1</sup>	PT	2	W
Non-repetitive reverse power surge <sup>*2</sup>	PZSM	100	W
Electrostatic discharge <sup>*3</sup>	ESD	±30	kV
Junction temperature	T <sub>j</sub>	150	°C
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note: \*1 Mounted on ceramics print circuit board.

Board size: 50 mm × 50 mm

Board thickness: 0.8 mm

Soldering size: 2 mm × 2 mm

\*2 t = 0.1ms

\*3 Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 200 mA			1.2	V
Zener voltage <sup>*1, *2</sup>	VZ	IZ = 10 mA	5.89	6.20	6.51	V
Zener operating resistance	RZ	IZ = 10 mA			30	Ω
Reverse current	IR	VR = 3.0 V			20	μA
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	IZ = 10 mA		2.2		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

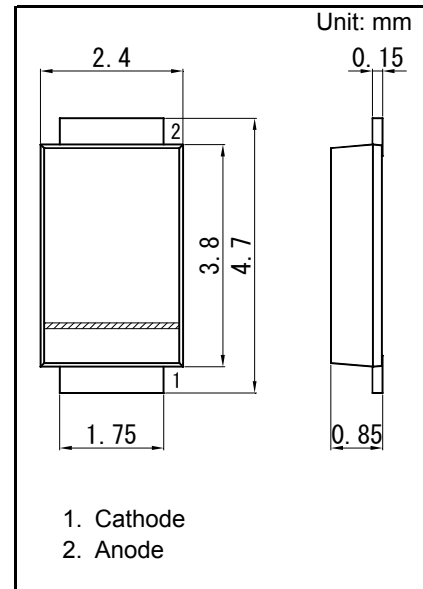
2. Absolute frequency of input and output is 5 MHz.

3. \*1 The temperature must be controlled 25°C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

\*2 VZ guaranteed 20 ms after current flow.

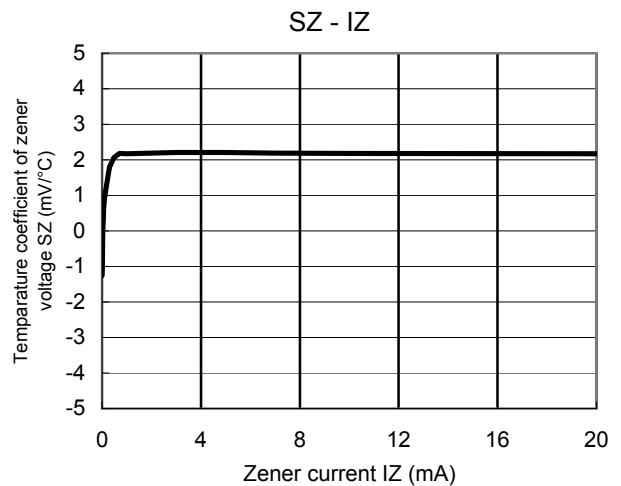
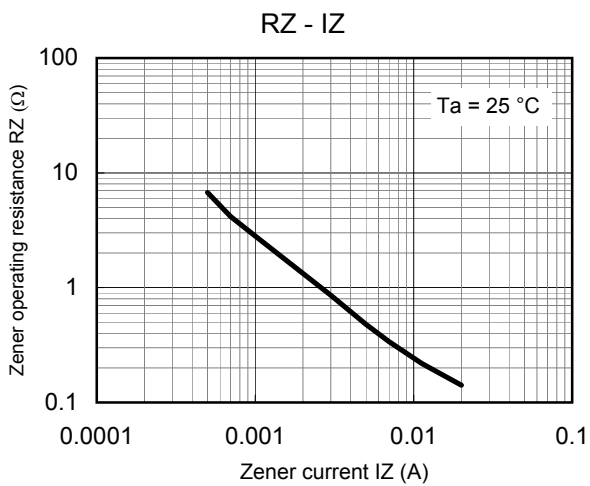
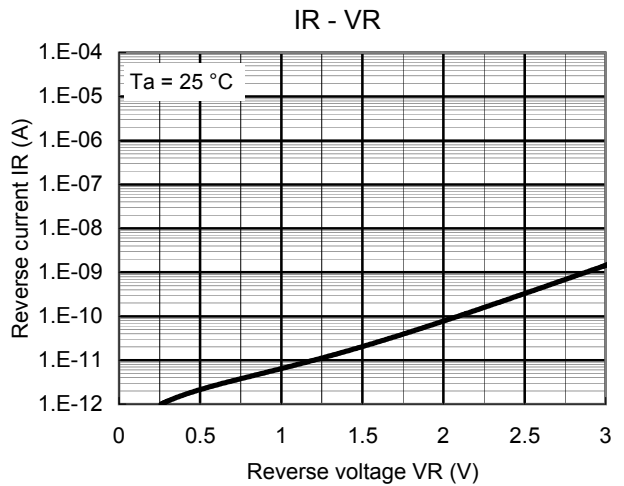
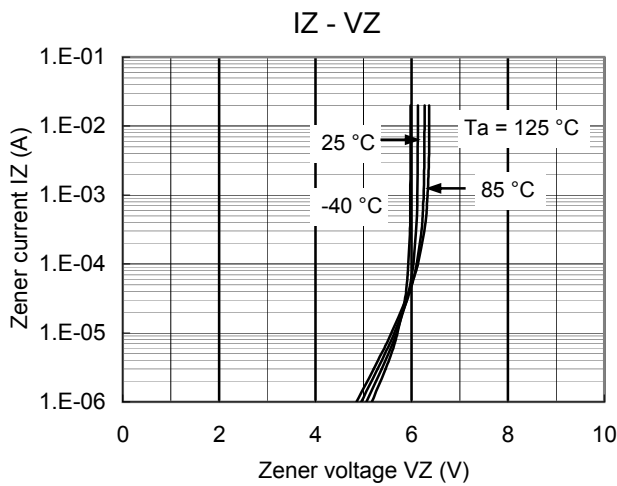
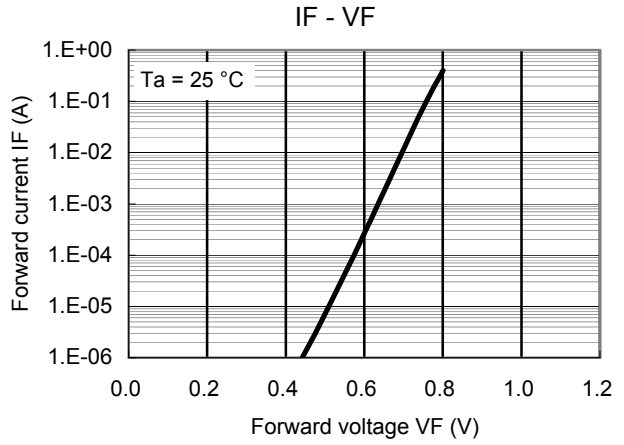
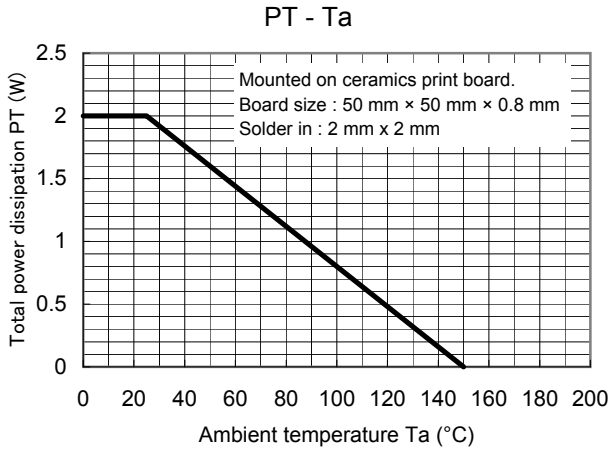
\*3 T<sub>j</sub> = 25°C to 150°C



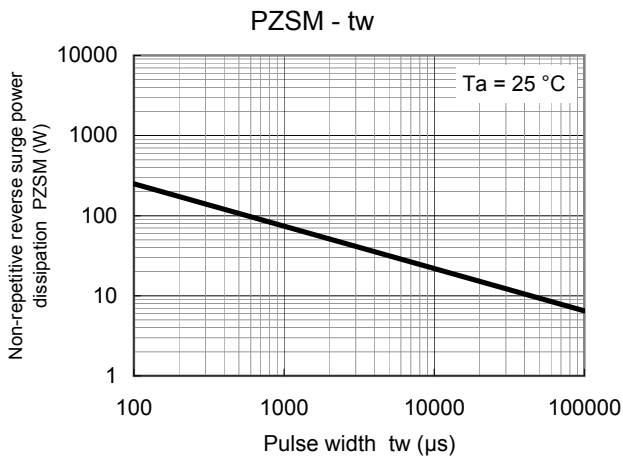
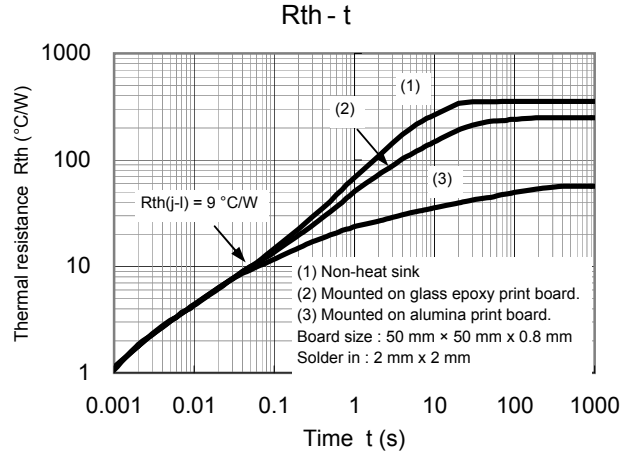
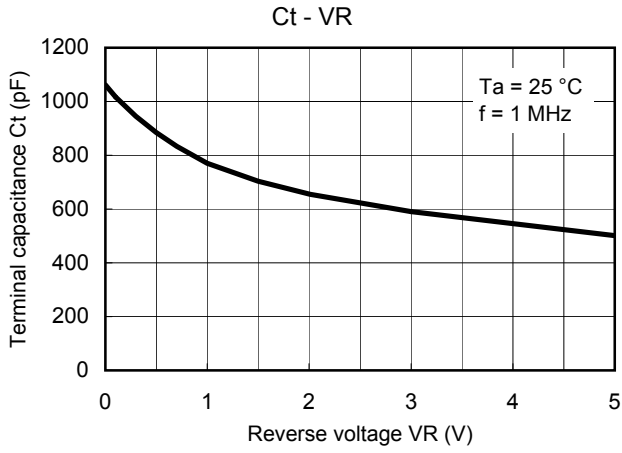
Panasonic	TMiniP2-F2-B
JEITA	SC-110A
Code	—



Technical Data ( reference )



Technical Data ( reference )



TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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